

Title (en)

Platen of polishing apparatus and method of adhesion of polishing pad

Title (de)

Poliervorrichtungsscheibe und Verfahren zum Aufkleben eines Polierkissens

Title (fr)

Plateau d'un dispositif de polissage et procédé de collage d'un tampon de polissage

Publication

**EP 0943397 A2 19990922 (EN)**

Application

**EP 99103955 A 19990309**

Priority

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Abstract (en)

A platen of a polishing apparatus and a method of adhesion of a polishing pad enables a polishing pad to be adhered to the platen and cut easily and in a short time even by an unskilled worker. Protective rings are attached to the upper part of the outer peripheral surface and upper part of the inner peripheral surface of a platen covered by a protective film over its entire surface other than the pad adhesion surface. At this time, the pad abutting surfaces of the protective rings are set to be level with the pad adhesion surface. An original sheet of a polishing pad larger than the platen is adhered to the pad adhesion surface in this state, then the blade part of a cutter is used to cut the polishing pad while abutting against the slanted surfaces of the protective rings, whereby the polishing pad can be cut to a shape corresponding to the platen. <IMAGE>

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